

Taiwan-Asia Semiconductor Corporation

Investor Conference

2022/11/22

Safe Harbor Statement

- This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.
- Except as required by law, we undertake no obligation to update any forward-looking statements, whether as a result of new information, future events or otherwise.

Company Overview

Company Profile

Nov. 2021
Renamed TASC
Formerly named: OPTO
TECH CORPORATION

Mar. 2022
Subsidiary Established
- 「PASC」

Jan. 2022
Split the system business group
Subsidiary Established - 「OPTO
TECH CORPORATION」

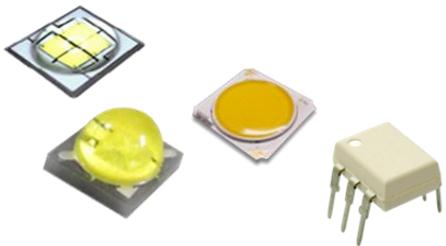
Nov. 2022
Invest in the Compound
Semiconductor products

Products



System Products

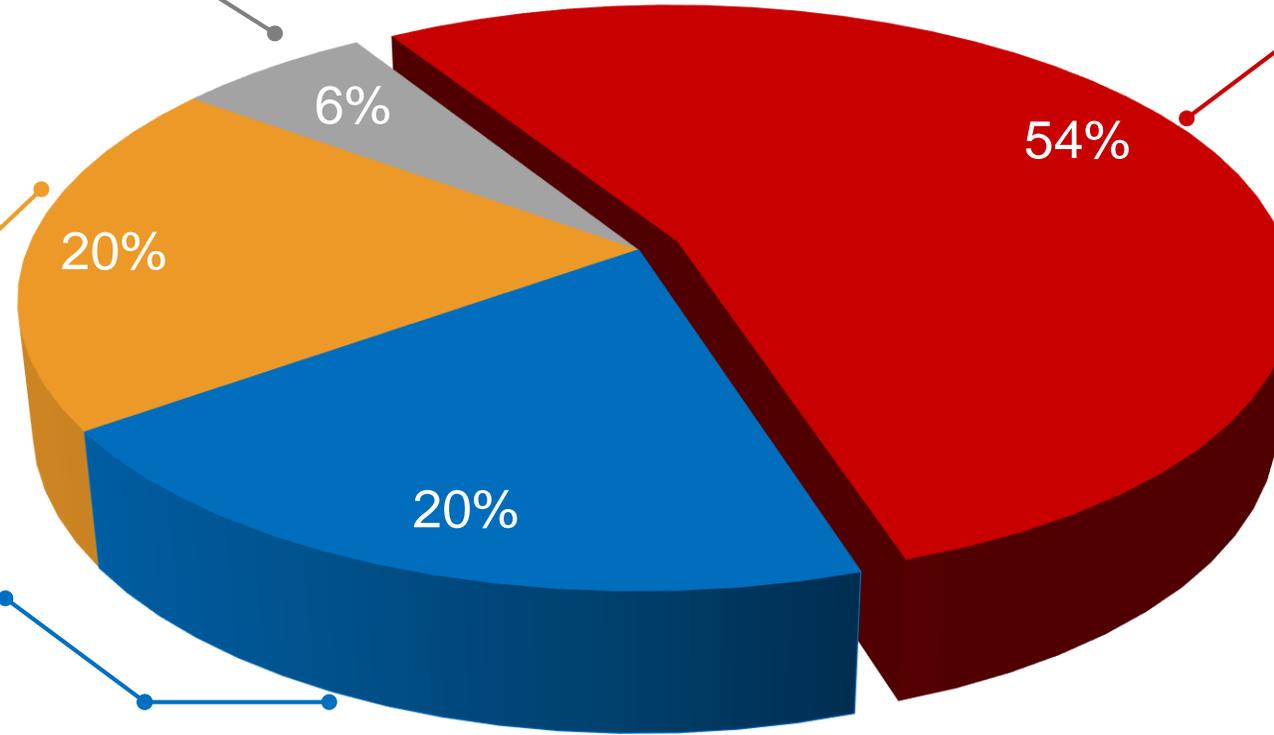
LED Chips



Sensor Chips

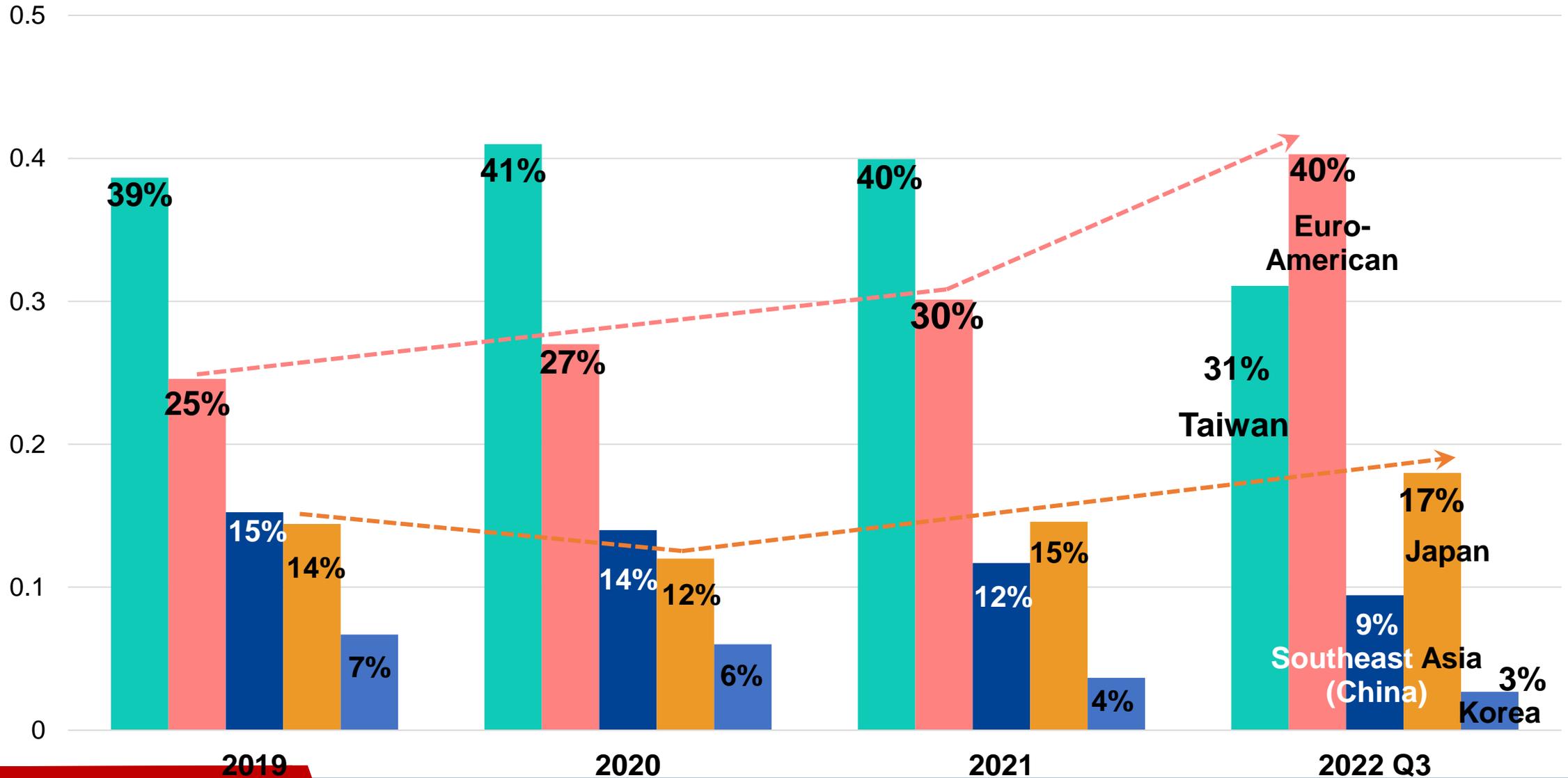


Others

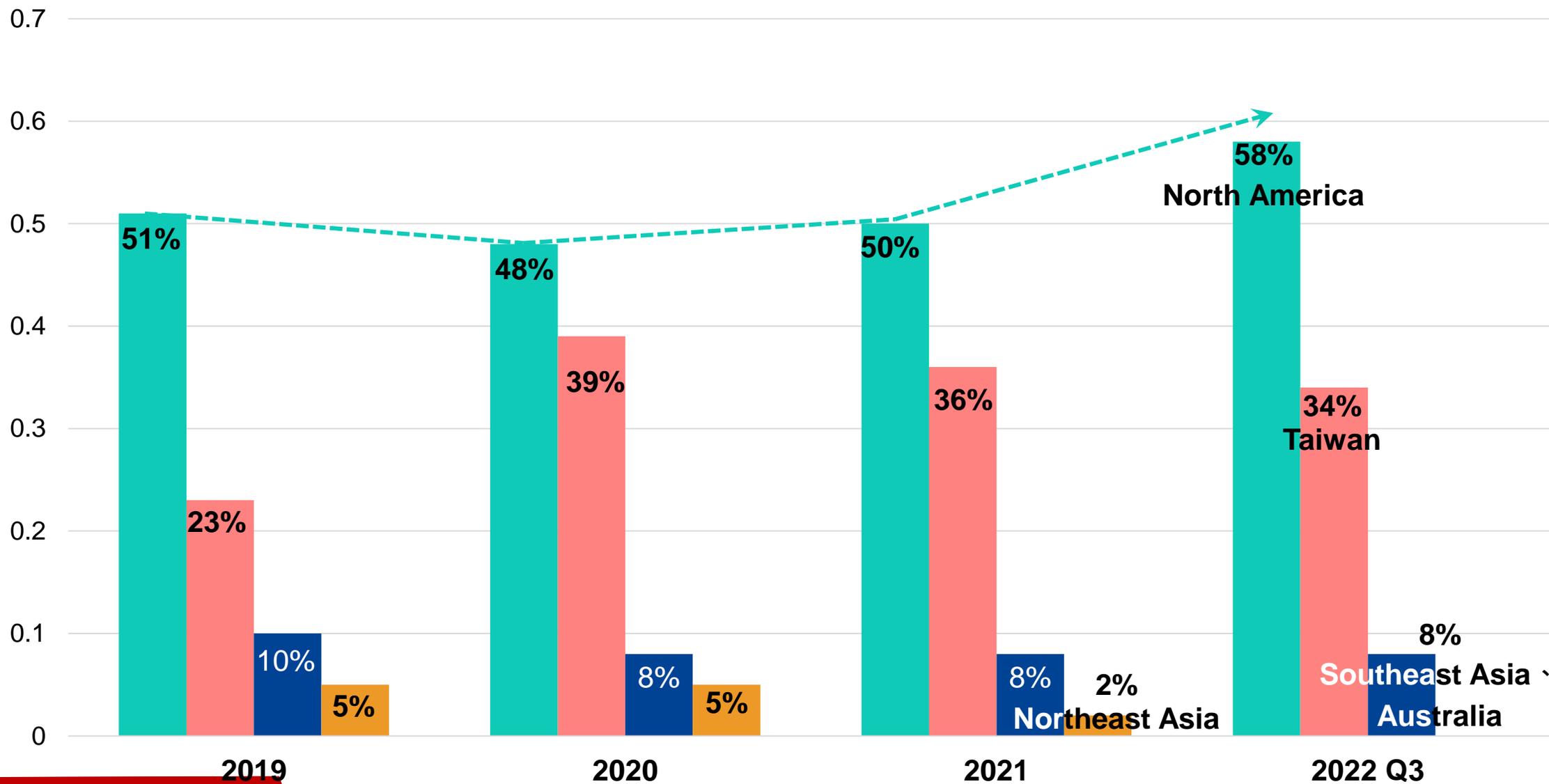


■ Sensor Chips ■ LED Chips ■ System Products ■ Others

LED Chips & Sensor Chips Product sales Breakdown by Area



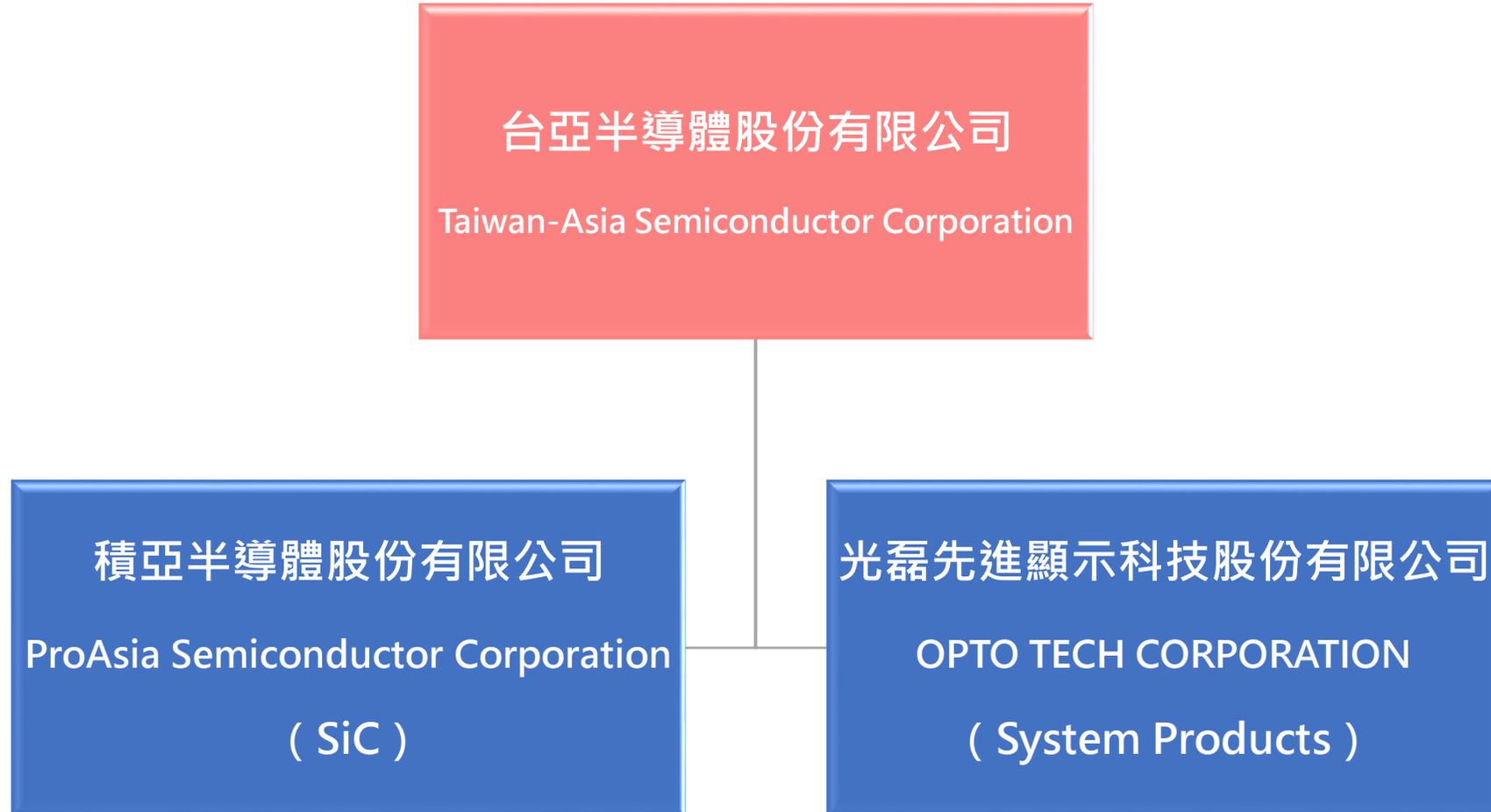
System Products Product sales Breakdown by Area



Business Strategies and Trends

- **Business strategies, market trends, product portfolio**

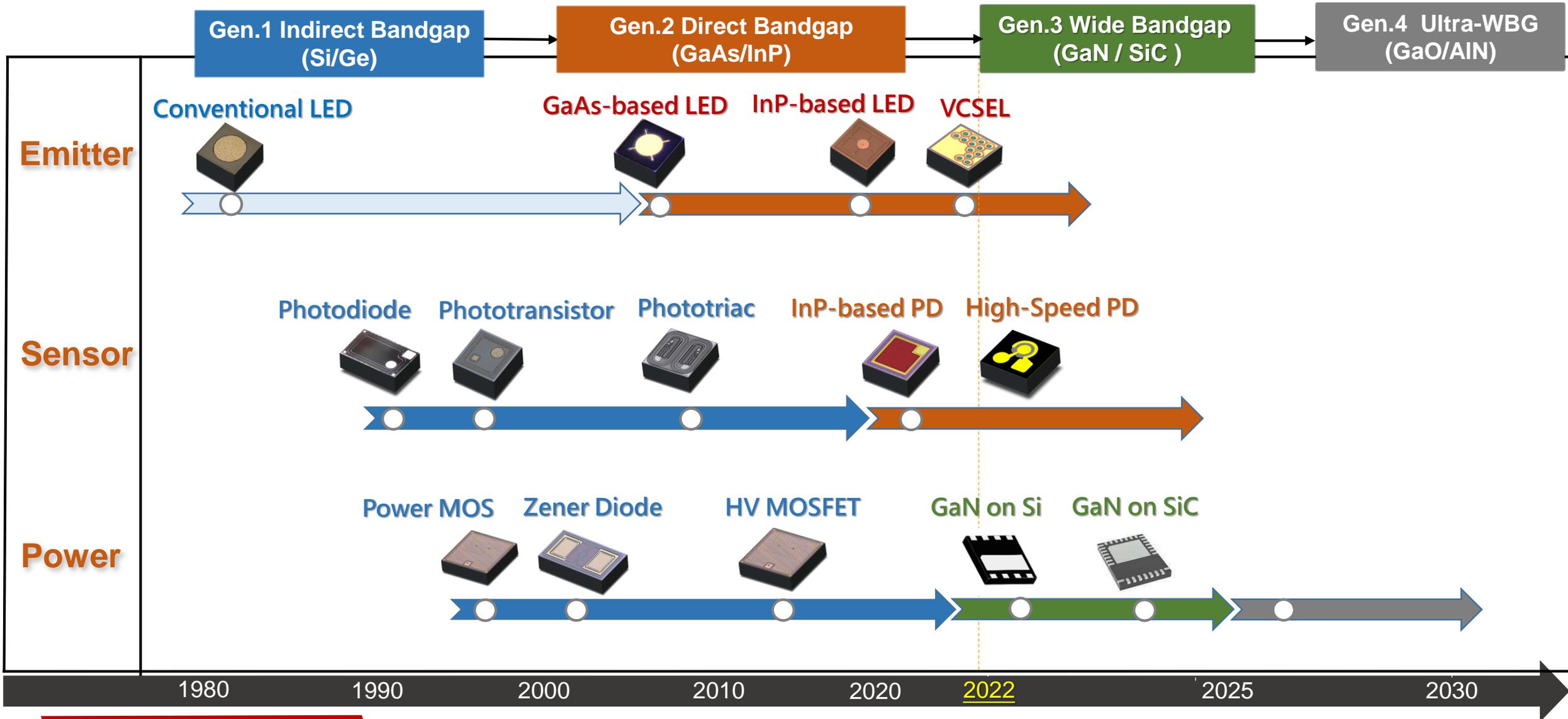
Investment Structure



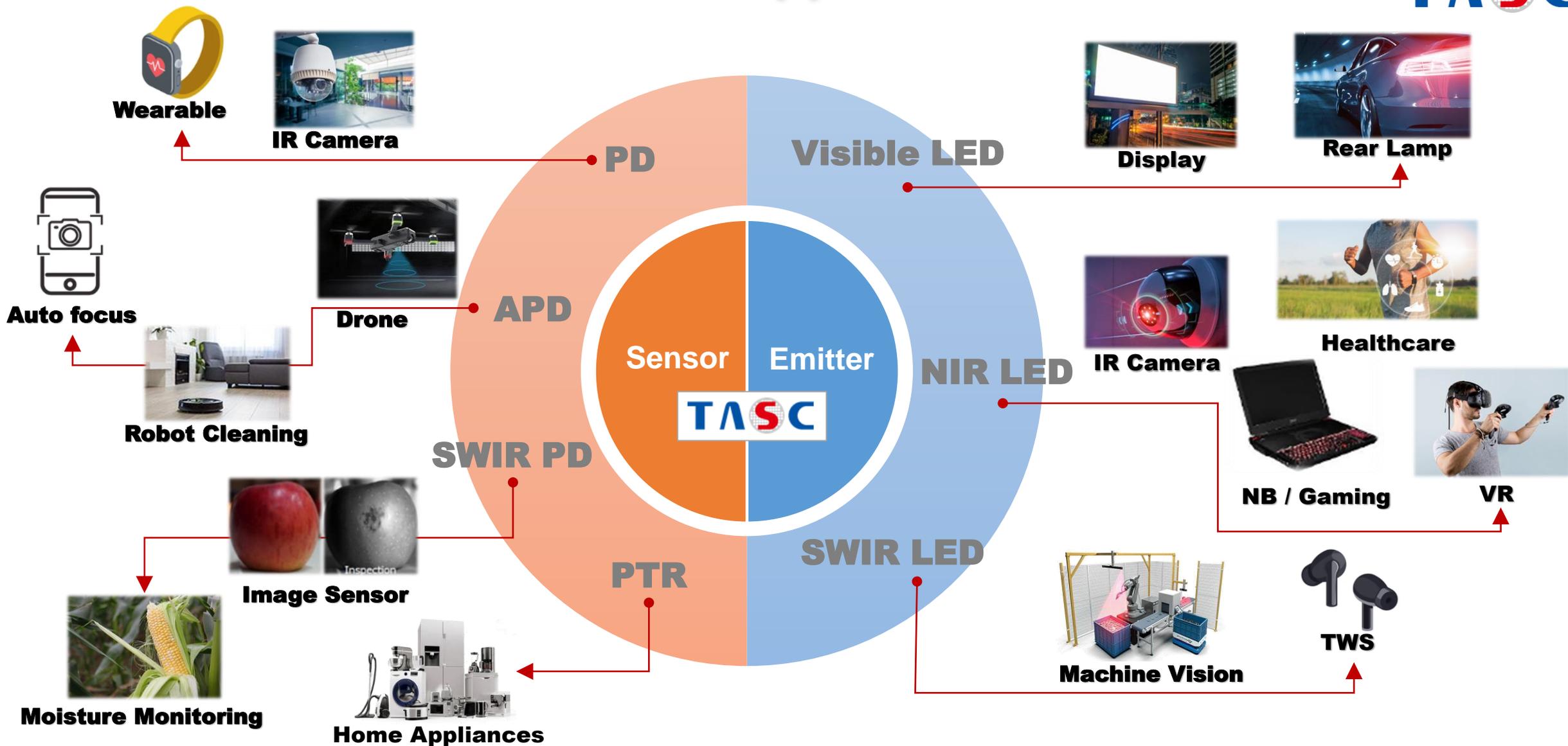
TASC Business Operation Strategy



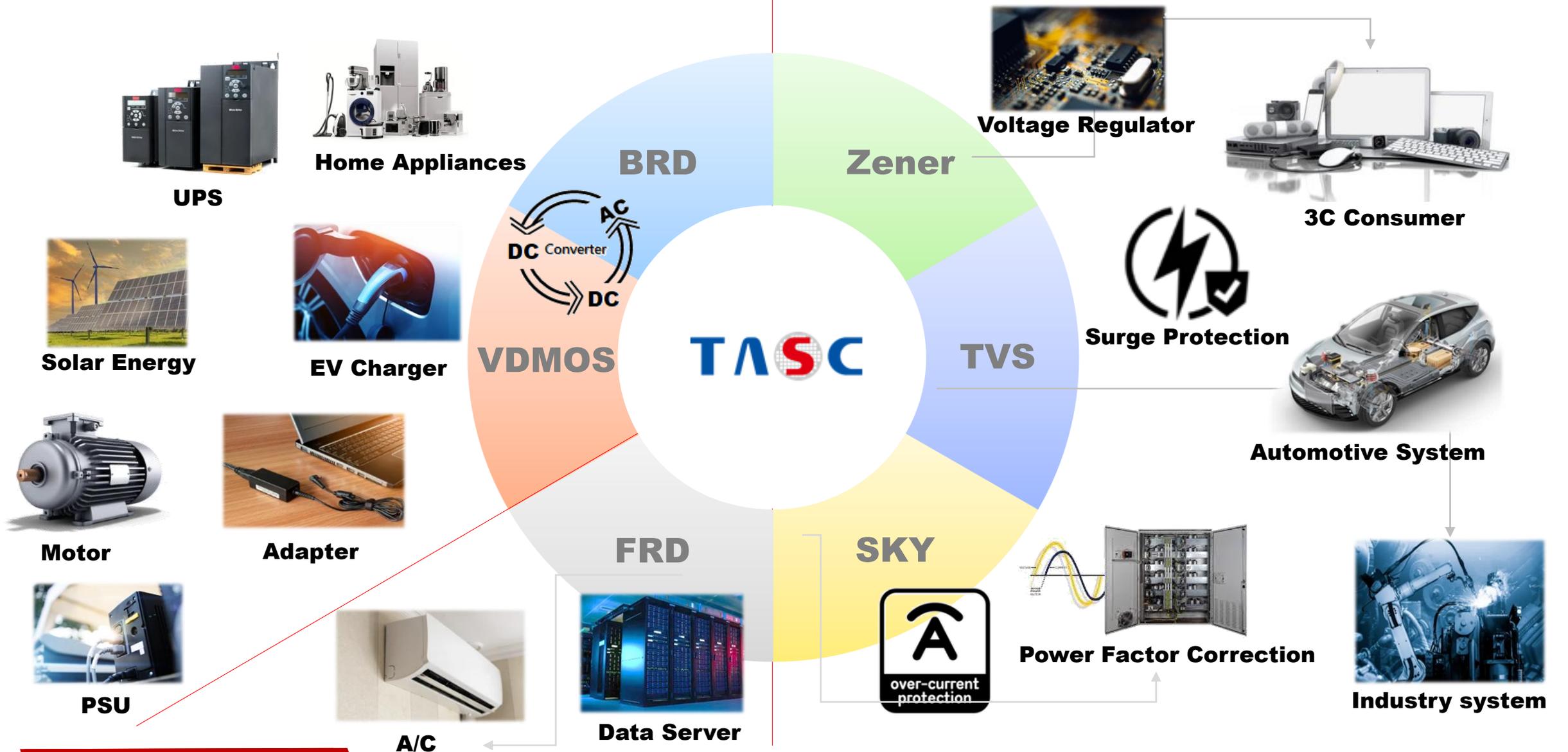
Three Major Product Group Roadmap



Sensor and Emitter Product Applications

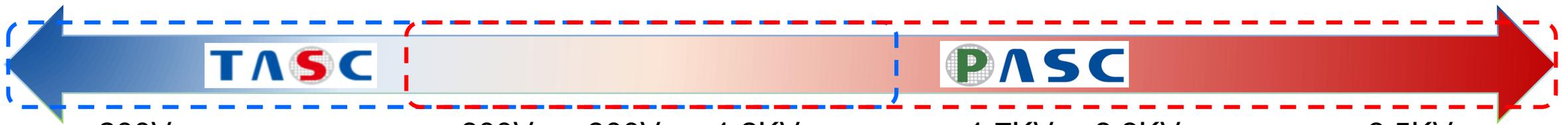


Si Power Device Product Applications



GaN-on-Si and SiC Product Applications

 Fast Charger	 Lighting Driver	 EV OBC	 Motor	 EV Charger	 Wind Energy	 Smart Power Grid	 High Speed Rail
 Wireless Charger	 Data Server	 EV Inverter	 Solar Inverter	 PV System	 Industry Drivers		 Ships & Vessels
 Laptop Adapter	 Class D Audio	 Home Appliances	 Robotics	 UPS	 Energy Storage	 Welding	 Induction Heating



<200V

600V

900V

1.2KV

1.7KV

3.3KV

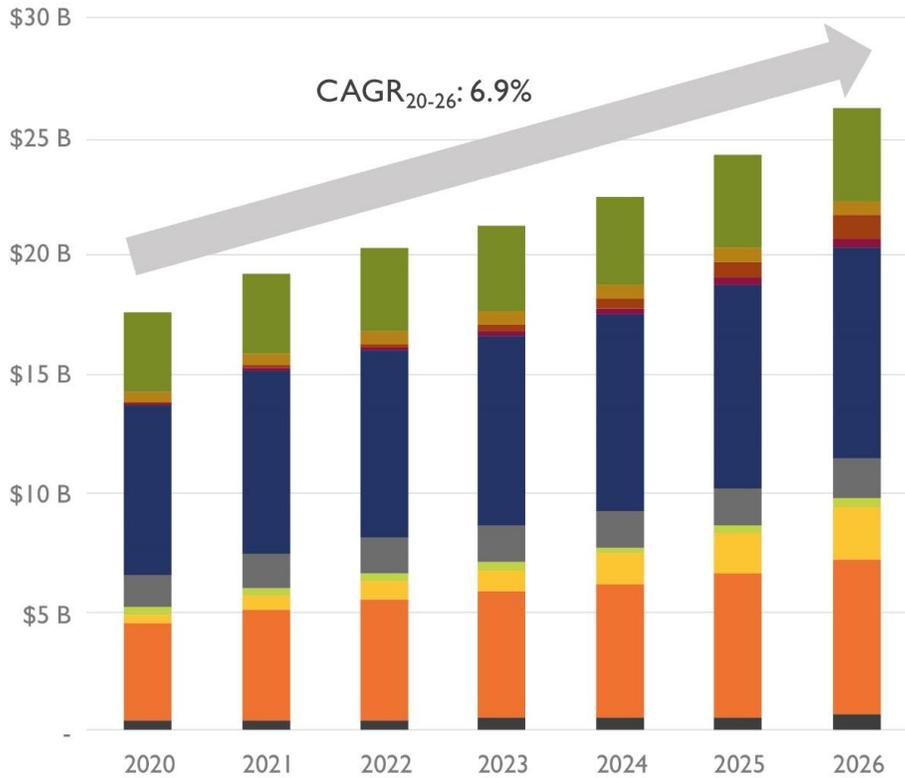
>6.5KV

GaN

SiC

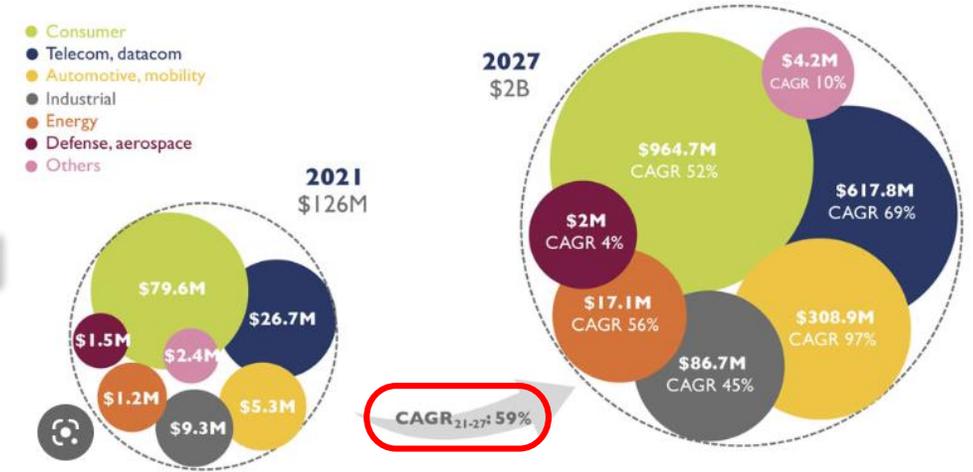
Analysis of Power Device Market

(Source: Status of the Power Electronics Industry 2021 report, Yole Développement, 2021)



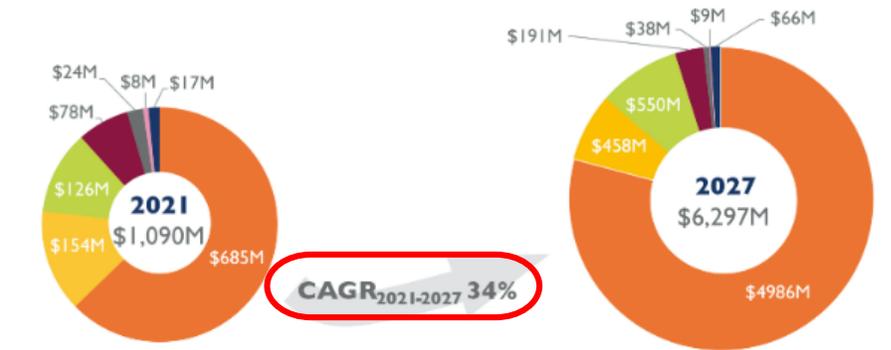
2021-2027 power GaN device market revenue

(Source: Power GaN 2022 report, Yole Développement, 2022)

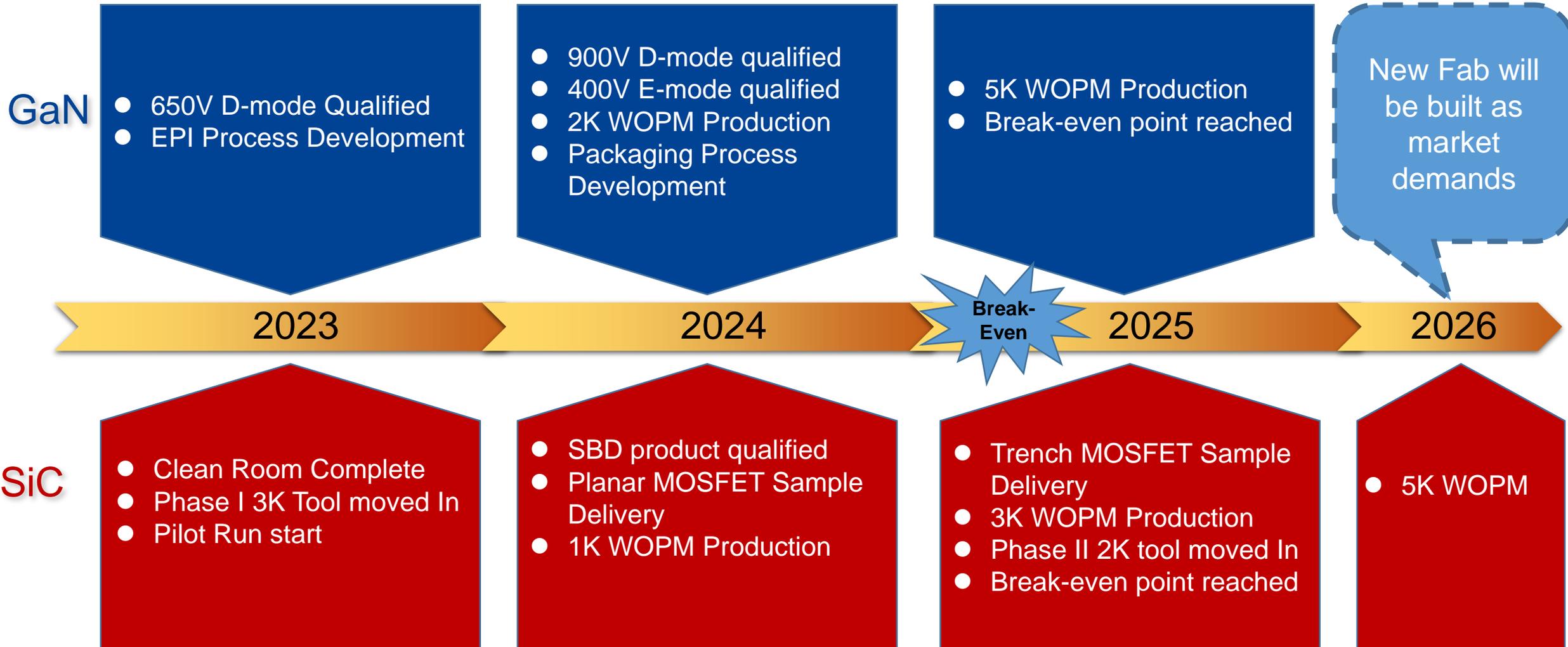


2021-2027 power SiC market devices split by segment

(Source: Power SiC 2022 report, Yole Développement, 2022)

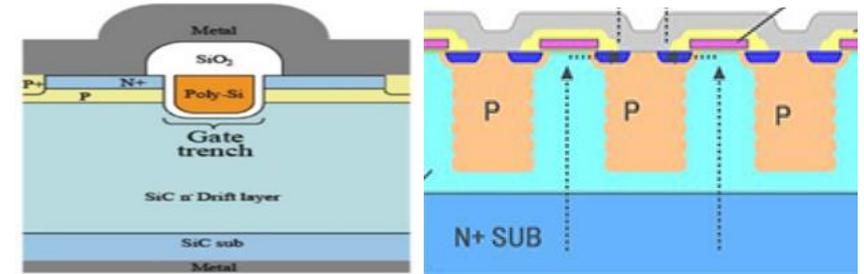


GaN/SiC Product Development Milestones

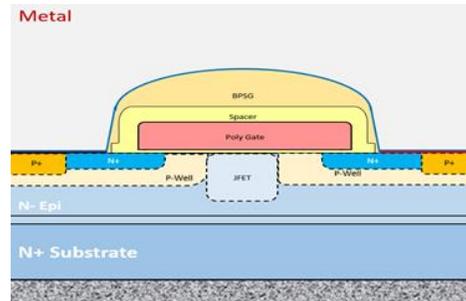


PASC SiC Technology Roadmap

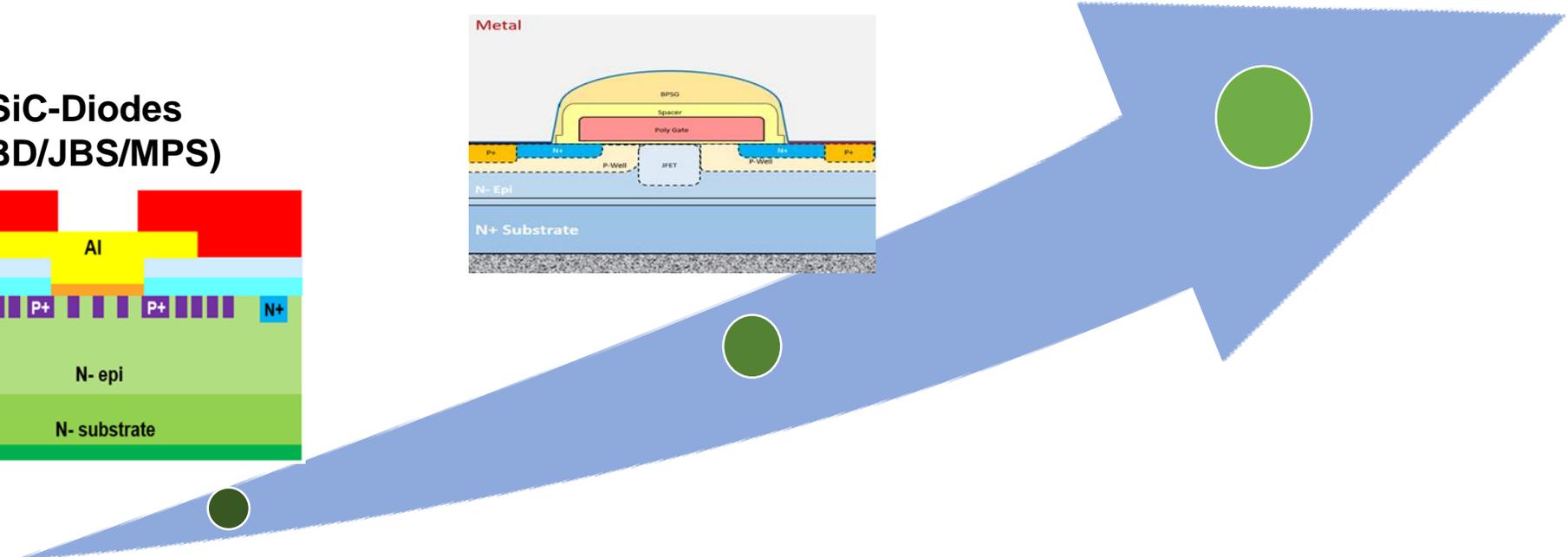
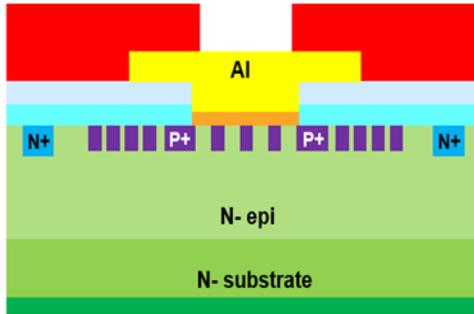
New Technologies: Trench, Superjunction



SiC-MOSFET (Planar Power MOSFET)



SiC-Diodes (SBD/JBS/MPS)

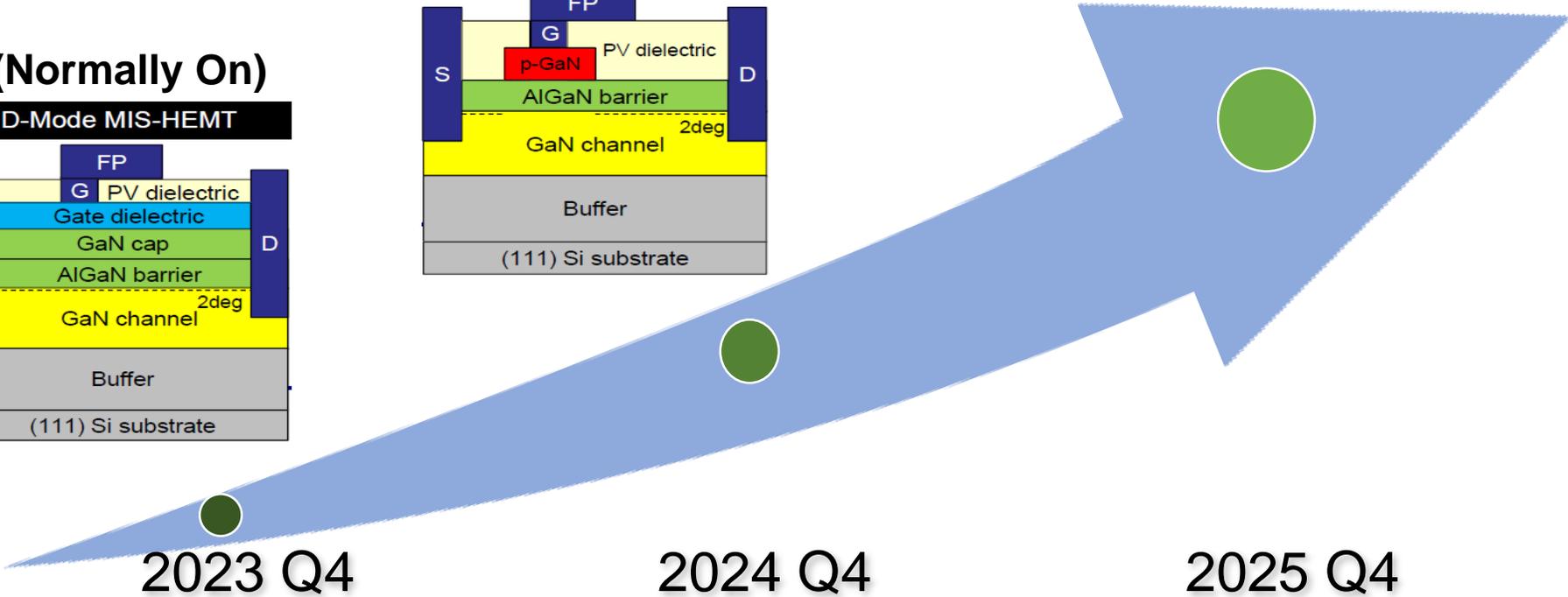
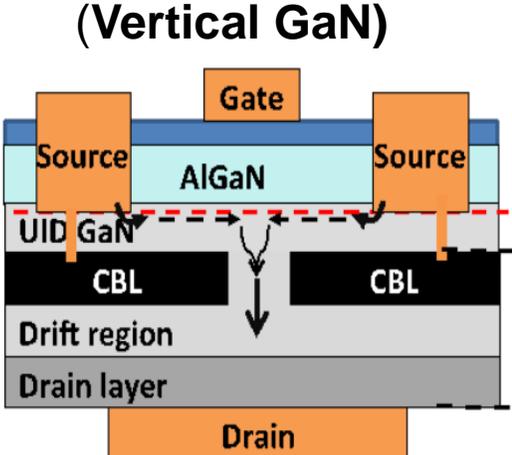
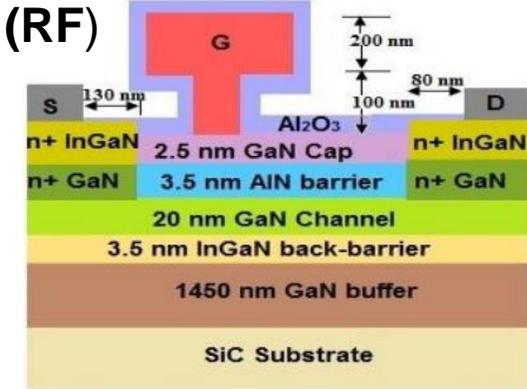
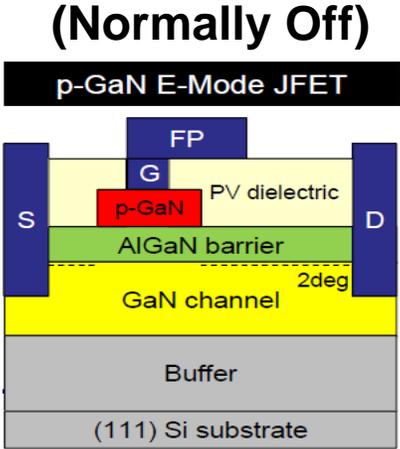
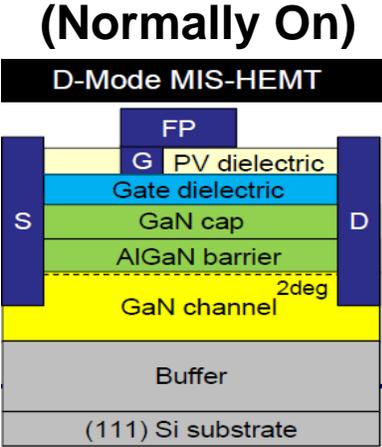


2024 Q4

2025 Q4

2026 Q4

TASC GaN-on-Si Technology Roadmap



2023 Q4

2024 Q4

2025 Q4

Summary

- TASC will continue to provide more competitive products in the existing sensor and emitter markets.
- In response to market and customer demands, TASC Group will increase invest especially on GaN and SiC power devices, to diversify product portfolio and gain more market share in power electronics.
- The synergy between existing sensors and GaN/SiC power devices will create a variety of new products, maximize the revenue and profit margin with existing manufacturing capacity.

Q & A